

/ Descriptions

KF 50) CD GE G Silicon PNP transistor in a TO-92LM Plastic Package.

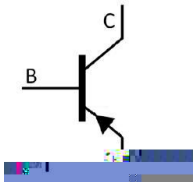
/ Features

)J: (*/*
Complementary pair with 2SC1383.

/ Applications

AF power amplifier and driver.

/ Equivalent Circuit



/ Pinning



PIN1 Base PIN 2 Collector PIN 3 Emitter

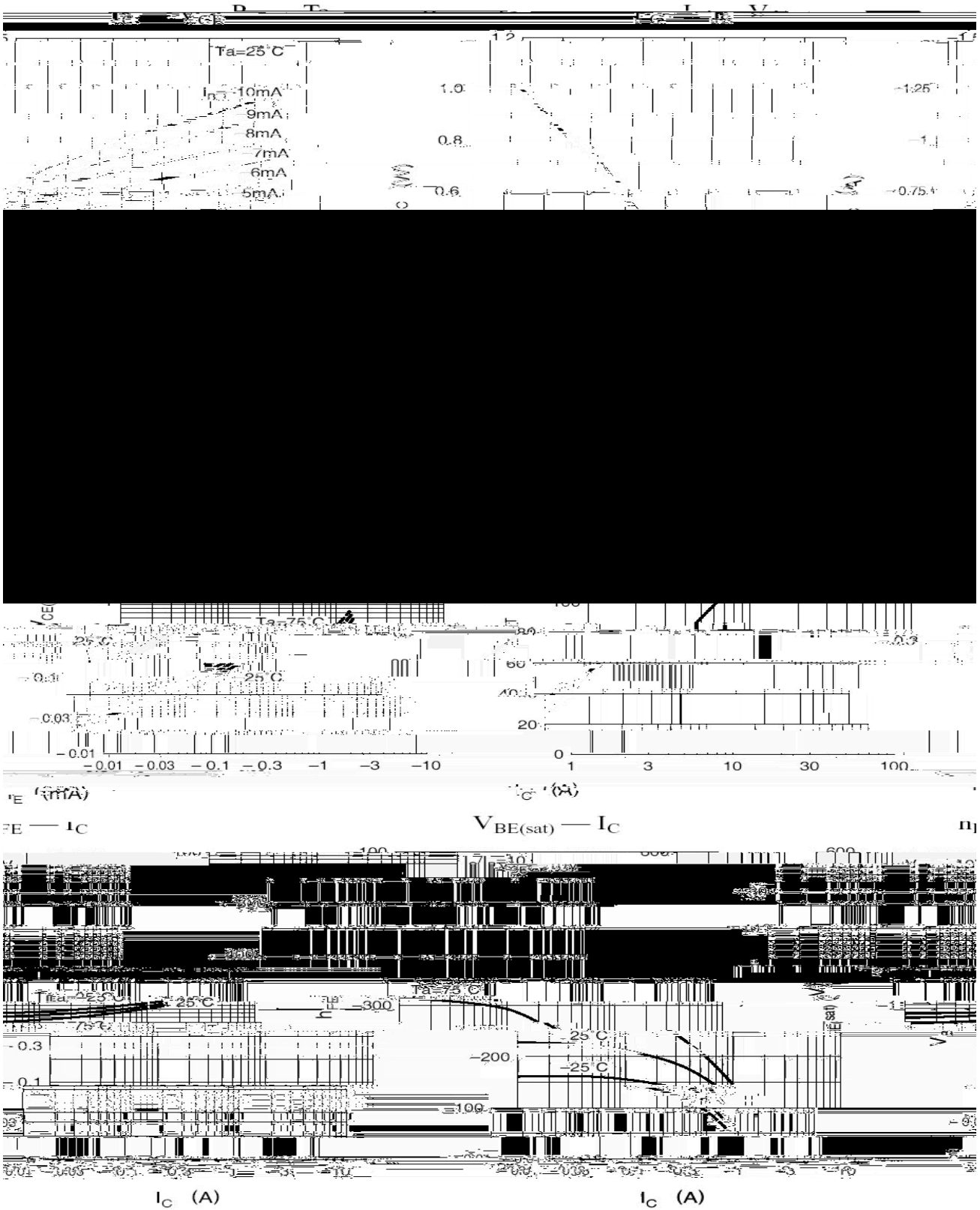
/ h_{FE} Classifications & Marking

h_{FE} Classifications Symbol	Q	R	S
h_{FE} Range	85~170	120~240	170~340

Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	-30	V
Collector to Emitter Voltage	V_{CEO}	-25	V
Emitter to Base Voltage	V_{EBO}	-5.0	V
Collector Current - Continuous	I_C	-1.0	A
Collector Current – Continuous(Pulse)	I_{CP}	-1.5	A
Collector Power Dissipation	P_C	1.0	W
Junction Temperature	T_j	150	
Storage Temperature Range	T_{stg}	-55 150	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector to Base Breakdown Voltage	V_{CBO}	$I_C = -10\text{ A}$ $I_E = 0$	-30			V

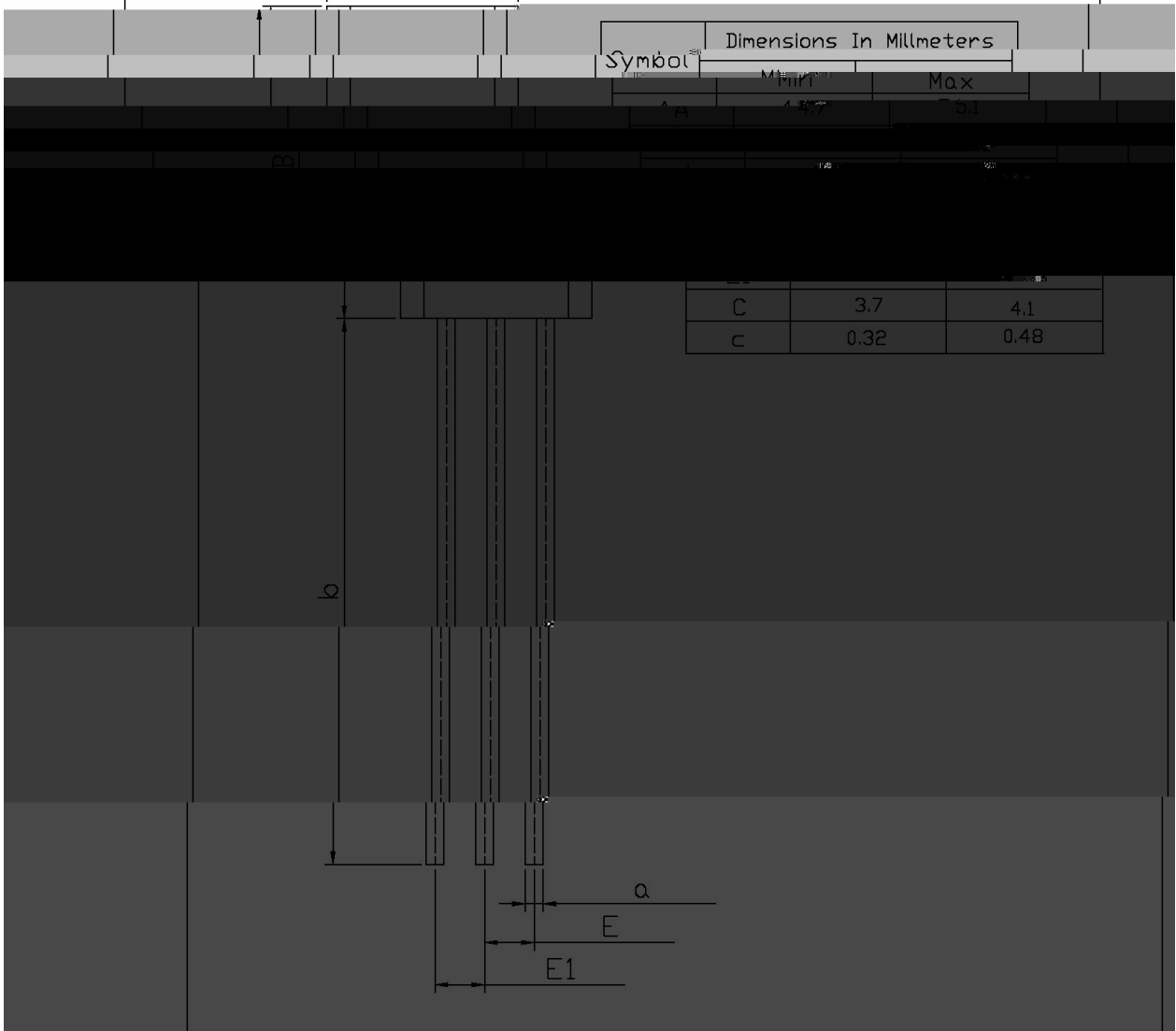
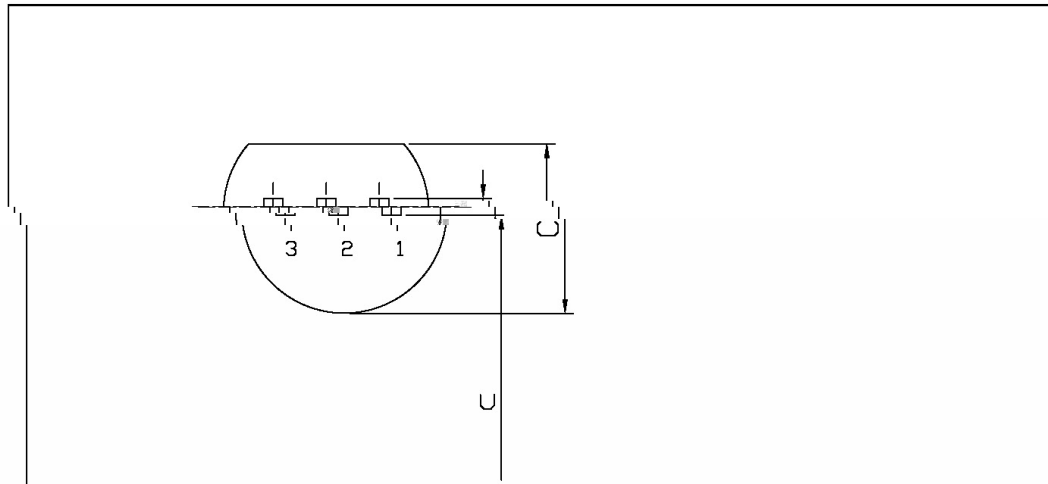
/ Electrical Characteristic Curve



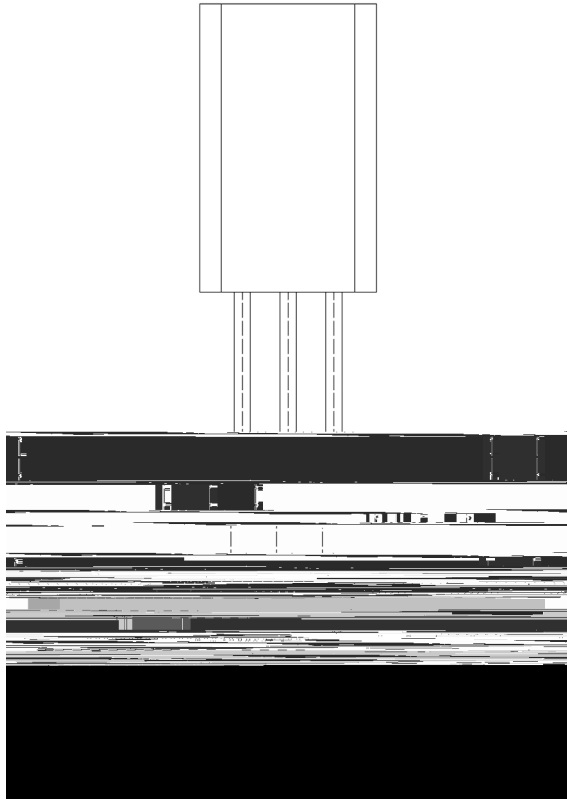
/ Package Dimensions

TO-92LM

Unit: mm

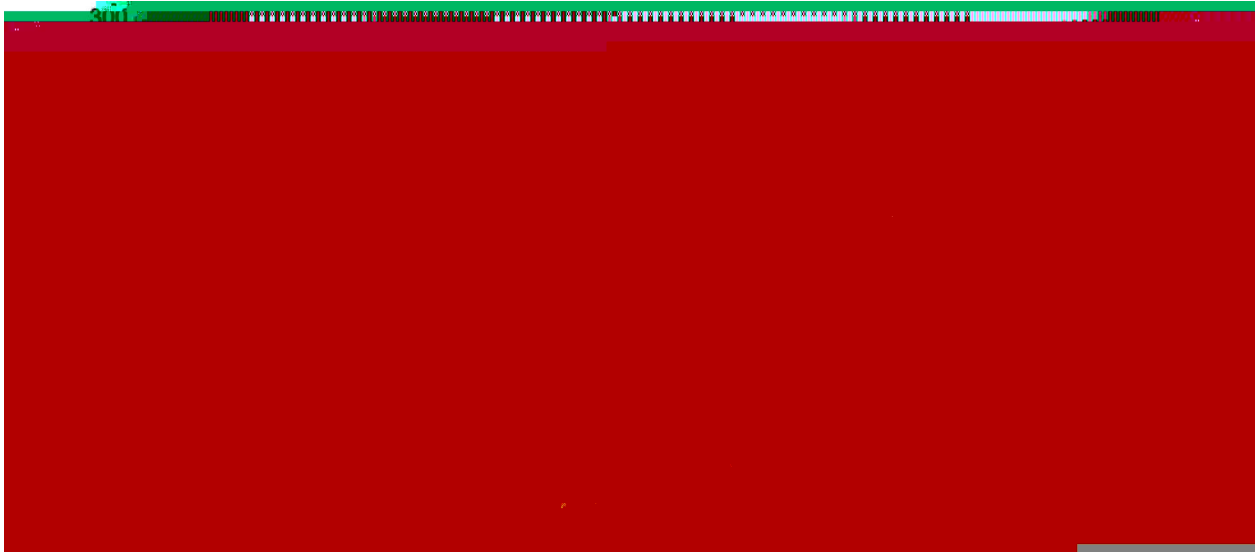


/ Marking Instructions



91 1
8-/*
H1

() / Temperature Profile for Dip Soldering(Pb-Free)



- | | | | | | | |
|---|--------|-----|------------|----------|---|--------------------------------------|
| 1 | 25 | 150 | 60 | 90sec; | Note: | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 255..5 | | 5..0.5sec; | | 2.Peak Temp.:255..5 , Duration:5..0.5sec. | |
| 3 | | | 2 | 10 /sec. | 3. Cooling Speed: 2~10 /sec. | |

/ Resistance to Soldering Heat Test Conditions

270..5 10...1 sec. Temp.:270..5 Time:10...1 sec

/ Packaging SPEC.

/ BULK

Package Type	Units	Dimension	(unit mm3)
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